



# ST083S SERIES

## INVERTER GRADE THYRISTORS

### Stud Version

#### Features

- All diffused design
- Center amplifying gate
- Guaranteed high dv/dt
- Guaranteed high di/dt
- High surge current capability
- Low thermal impedance
- High speed performance

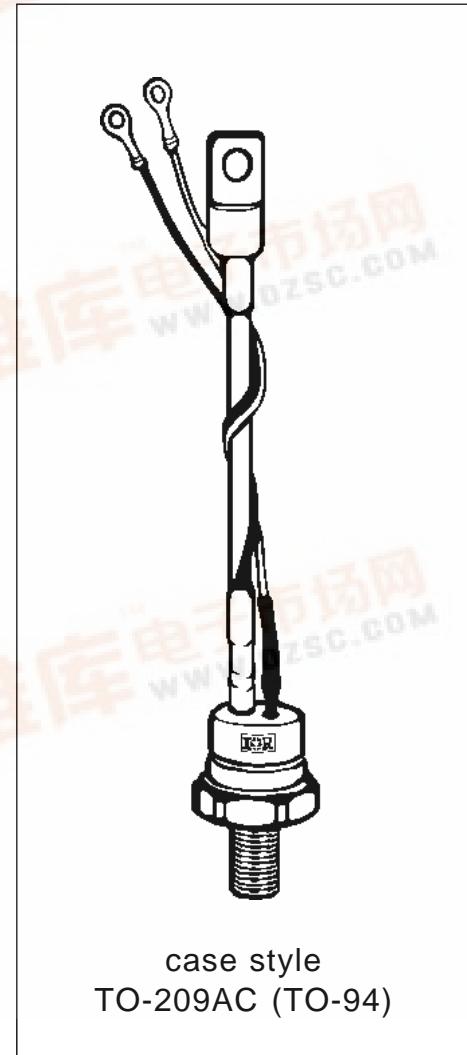
85A

#### Typical Applications

- Inverters
- Choppers
- Induction heating
- All types of force-commutated converters

#### Major Ratings and Characteristics

Parameters	ST083S	Units
I <sub>T(AV)</sub>	85	A
@ T <sub>C</sub>	85	°C
I <sub>T(RMS)</sub>	135	A
I <sub>TSM</sub>	2450	A
@ 50Hz	2450	A
@ 60Hz	2560	A
I <sup>2</sup> t	30	KA <sup>2</sup> s
@ 50Hz	30	KA <sup>2</sup> s
@ 60Hz	27	KA <sup>2</sup> s
V <sub>DRM</sub> /V <sub>RRM</sub>	400 to 1200	V
t <sub>q</sub> range (*)	10 to 30	μs
T <sub>J</sub>	- 40 to 125	°C



## ST083S Series

### ELECTRICAL SPECIFICATIONS

#### Voltage Ratings

Type number	Voltage Code	$V_{DRM}/V_{RRM}$ , maximum repetitive peak voltage V	$V_{RSM}$ , maximum non-repetitive peak voltage V	$I_{DRM}/I_{RRM}$ max. @ $T_J = T_{J\max}$ mA
ST083S	04	400	500	30
	08	800	900	
	10	1000	1100	
	12	1200	1300	

#### Current Carrying Capability

Frequency				Units			
50Hz	210	120	330	270	2540	1930	A
400Hz	200	120	350	210	1190	810	
1000Hz	150	80	320	190	630	400	
2500Hz	70	25	220	85	250	100	
Recovery voltage $V_r$	50	50	50	50	50	50	V
Voltage before turn-on $V_d$	$V_{DRM}$	$V_{DRM}$	$V_{DRM}$	$V_{DRM}$			
Rise of on-state current $dI/dt$	50	50	-	-	-	-	A/ $\mu$ s
Case temperature	60	85	60	85	60	85	°C
Equivalent values for RC circuit	$22\Omega / 0.15\mu F$		$22\Omega / 0.15\mu F$		$22\Omega / 0.15\mu F$		

#### On-state Conduction

Parameter	ST083S	Units	Conditions			
$I_{T(AV)}$ Max. average on-state current @ Case temperature	85	A	180° conduction, half sine wave			
	85	°C				
$I_{T(RMS)}$ Max. RMS on-state current	135		DC @ 77°C case temperature			
$I_{TSM}$ Max. peak, one half cycle, non-repetitive surge current	2450					
	2560		t = 10ms	No voltage reapplied	Sinusoidal half wave, Initial $T_J = T_{J\max}$	
	2060					
	2160		t = 8.3ms	100% $V_{RRM}$ reapplied		
$^2t$ Maximum $I^2t$ for fusing	30		KA <sup>2</sup> s	t = 10ms		No voltage reapplied
	27			t = 8.3ms		reapplied
	21			t = 10ms		100% $V_{RRM}$ reapplied
	19			t = 8.3ms		reapplied
$I^2\sqrt{t}$ Maximum $I^2\sqrt{t}$ for fusing	300	KA <sup>2</sup> s	t = 0.1 to 10ms, no voltage reapplied			

## On-state Conduction

Parameter	ST083S	Units	Conditions
$V_{TM}$	Max. peak on-state voltage	V	$I_{TM} = 300A, T_J = T_J \text{ max}, t_p = 10\text{ms sine wave pulse}$
$V_{T(TO)1}$	Low level value of threshold voltage		$(16.7\% \times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)}, T_J = T_J \text{ max.})$
$V_{T(TO)2}$	High level value of threshold voltage		$(I > \pi \times I_{T(AV)}, T_J = T_J \text{ max.})$
$r_{t1}$	Low level value of forward slope resistance	$\text{m}\Omega$	$(16.7\% \times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)}, T_J = T_J \text{ max.})$
$r_{t2}$	High level value of forward slope resistance		$(I > \pi \times I_{T(AV)}, T_J = T_J \text{ max.})$
$I_H$	Maximum holding current	$\text{mA}$	$T_J = 25^\circ\text{C}, I_T > 30\text{A}$
$I_L$	Typical latching current		$T_J = 25^\circ\text{C}, V_A = 12\text{V}, R_a = 6\Omega, I_G = 1\text{A}$

## Switching

Parameter	ST083S	Units	Conditions
$di/dt$	Max. non-repetitive rate of rise of turned-on current	$\text{A}/\mu\text{s}$	$T_J = T_J \text{ max}, V_{DRM} = \text{rated } V_{DRM}$ $I_{TM} = 2 \times di/dt$
$t_d$	Typical delay time	$\mu\text{s}$	$T_J = 25^\circ\text{C}, V_{DM} = \text{rated } V_{DRM}, I_{TM} = 50\text{A DC}, t_p = 1\mu\text{s}$ Resistive load, Gate pulse: 10V, 5Ω source
$t_q$	Max. turn-off time (*)		$T_J = T_J \text{ max}, I_{TM} = 100\text{A, commutating } di/dt = 10\text{A}/\mu\text{s}$ $V_R = 50\text{V}, t_p = 200\mu\text{s}, dv/dt: \text{see table in device code}$

(\*)  $t_q = 10$  to  $20\mu\text{s}$  for 400 to 800V devices;  $t_q = 15$  to  $30\mu\text{s}$  for 1000 to 1200V devices.

## Blocking

Parameter	ST083S	Units	Conditions
$dv/dt$	Maximum critical rate of rise of off-state voltage	$\text{V}/\mu\text{s}$	$T_J = T_J \text{ max., linear to } 80\% V_{DRM}, \text{ higher value available on request}$
$I_{RRM}$ $I_{DRM}$	Max. peak reverse and off-state leakage current	$\text{mA}$	$T_J = T_J \text{ max, rated } V_{DRM}/V_{RRM} \text{ applied}$

## Triggering

Parameter	ST083S	Units	Conditions
$P_{GM}$	Maximum peak gate power	W	$T_J = T_J \text{ max, } f = 50\text{Hz, d\% = 50}$
$P_{G(AV)}$	Maximum average gate power		
$I_{GM}$	Max. peak positive gate current	A	$T_J = T_J \text{ max, } t_p \leq 5\text{ms}$
$+V_{GM}$	Maximum peak positive gate voltage	V	
$-V_{GM}$	Maximum peak negative gate voltage		$T_J = T_J \text{ max, } t_p \leq 5\text{ms}$
$I_{GT}$	Max. DC gate current required to trigger	$\text{mA}$	
$V_{GT}$	Max. DC gate voltage required to trigger		$T_J = 25^\circ\text{C, } V_A = 12\text{V, } R_a = 6\Omega$
$I_{GD}$	Max. DC gate current not to trigger	$\text{mA}$	
$V_{GD}$	Max. DC gate voltage not to trigger		$T_J = T_J \text{ max, rated } V_{DRM} \text{ applied}$

# ST083S Series

## Thermal and Mechanical Specifications

Parameter	ST083S	Units	Conditions
$T_J$	Max. junction operating temperature range	-40 to 125	°C
$T_{stg}$	Max. storage temperature range	-40 to 150	
$R_{thJC}$	Max. thermal resistance, junction to case	0.195	K/W
$R_{thCS}$	Max. thermal resistance, case to heatsink	0.08	
$T$	Mounting torque, $\pm 10\%$	15.5 (137)	Nm (lbf-in)
		14 (120)	Nm (lbf-in)
wt	Approximate weight	130	g
Case style		TO-209AC (TO-94)	See Outline Table

## $\Delta R_{thJC}$ Conduction

(The following table shows the increment of thermal resistance  $R_{thJC}$  when devices operate at different conduction angles than DC)

Conduction angle	Sinusoidal conduction	Rectangular conduction	Units	Conditions
180°	0.034	0.025	K/W	$T_J = T_{J \text{ max.}}$
120°	0.041	0.042		
90°	0.052	0.056		
60°	0.076	0.079		
30°	0.126	0.127		

## Ordering Information Table

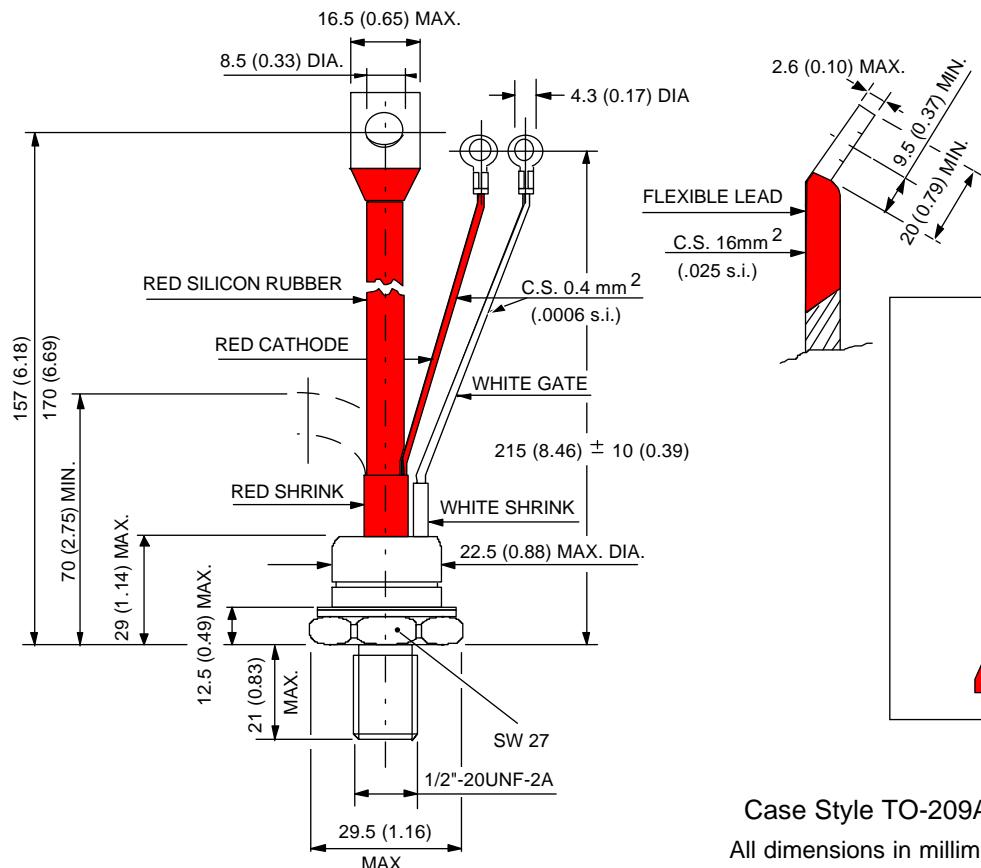
Device Code	ST	08	3	S	12	P	F	K	0	
	1	2	3	4	5	6	7	8	9	10
1	- Thyristor									
2	- Essential part number									
3	- 3 = Fast turn off									
4	- S = Compression bonding Stud									
5	- Voltage code: Code x 100 = $V_{RRM}$ (See Voltage Ratings Table)									
6	- P = Stud Base 1/2" 20UNF									
7	- Reapplied dv/dt code (for $t_q$ Test Condition)									
8	- $t_q$ code									
9	- 0 = Eyelet terminals (Gate and Aux. Cathode Leads)									
	1 = Fast-on terminals (Gate and Aux. Cathode Leads)									
	2 = Flag terminals (For Cathode and Gate Terminals)									
10	- Critical dv/dt:									
	None = 500V/ $\mu$ sec (Standard value)									
	L = 1000V/ $\mu$ sec (Special selection)									

dv/dt - $t_q$ combinations available						
$t_q$ ( $\mu$ s)	dv/dt (V/ $\mu$ s)	20	50	100	200	400
	10	CN	DN	EN	<b>FN *</b>	HN
	12	CM	DM	EM	<b>FM *</b>	HM
up to 800V	15	CL	DL	EL	FL	HL
	18	CP	DP	EP	<b>FP *</b>	HP
	20	CK	DK	EK	<b>FK *</b>	HK
$t_q$ ( $\mu$ s)	15	CL	--	--	<b>FN *</b>	--
	18	CP	DP	EP	<b>FM *</b>	--
only for	20	CK	DK	EK	<b>FK *</b>	HK
1000/1200V	25	CJ	DJ	EJ	FJ	HJ
	30	--	DH	EH	FH	HH

\*Standard part number.

All other types available only on request.

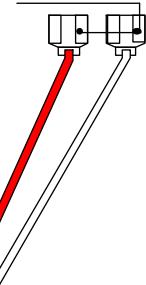
## Outline Table

CERAMIC HOUSING

Fast-on Terminals

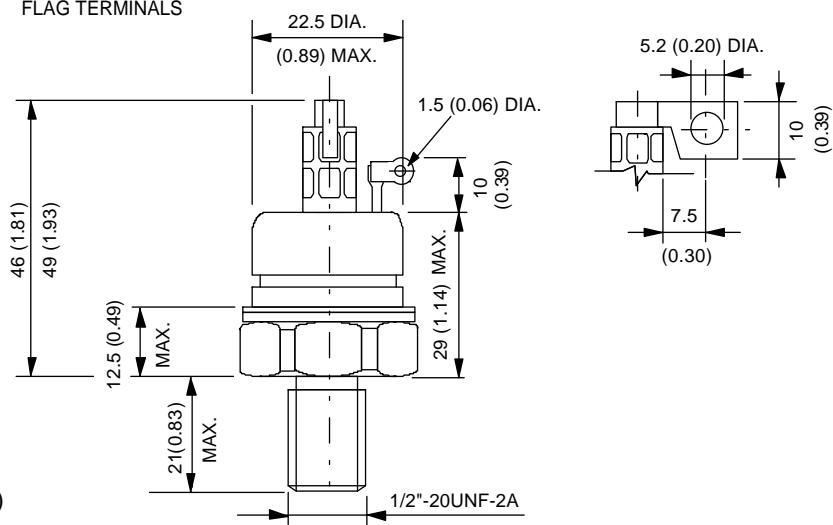
AMP. 280000-1

REF-250



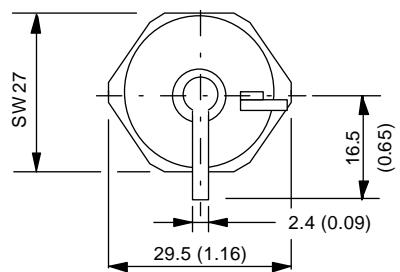
Case Style TO-209AC (TO-94)

All dimensions in millimeters (inches)

CERAMIC HOUSINGFLAG TERMINALS

Case Style TO-208AD (TO-83)

All dimensions in millimeters (inches)



## ST083S Series

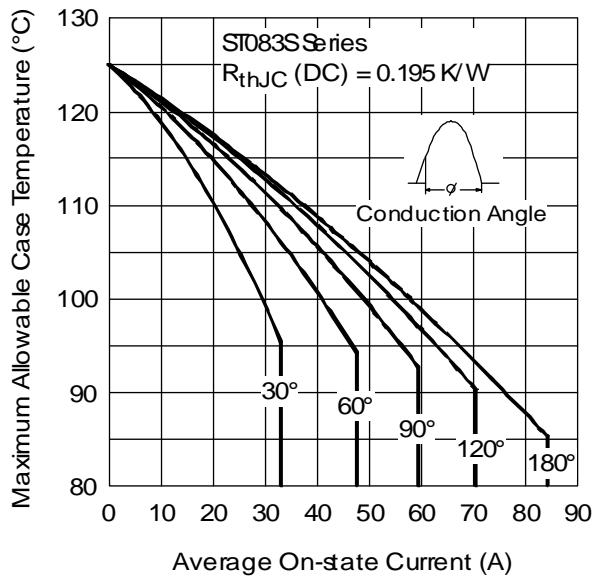


Fig. 1 - Current Ratings Characteristics

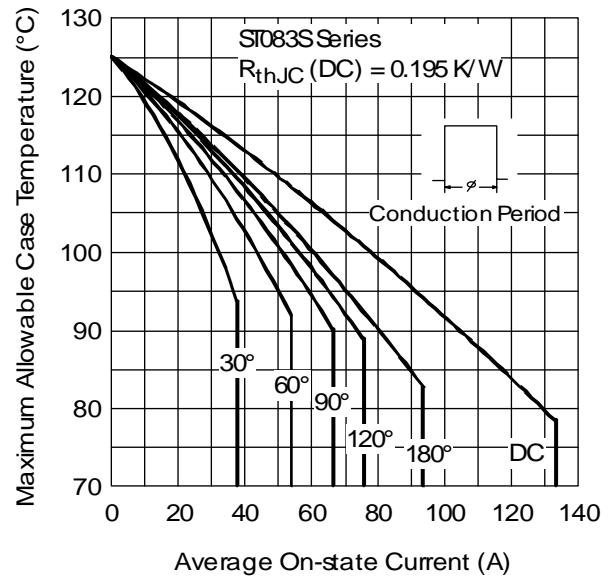


Fig. 2 - Current Ratings Characteristics

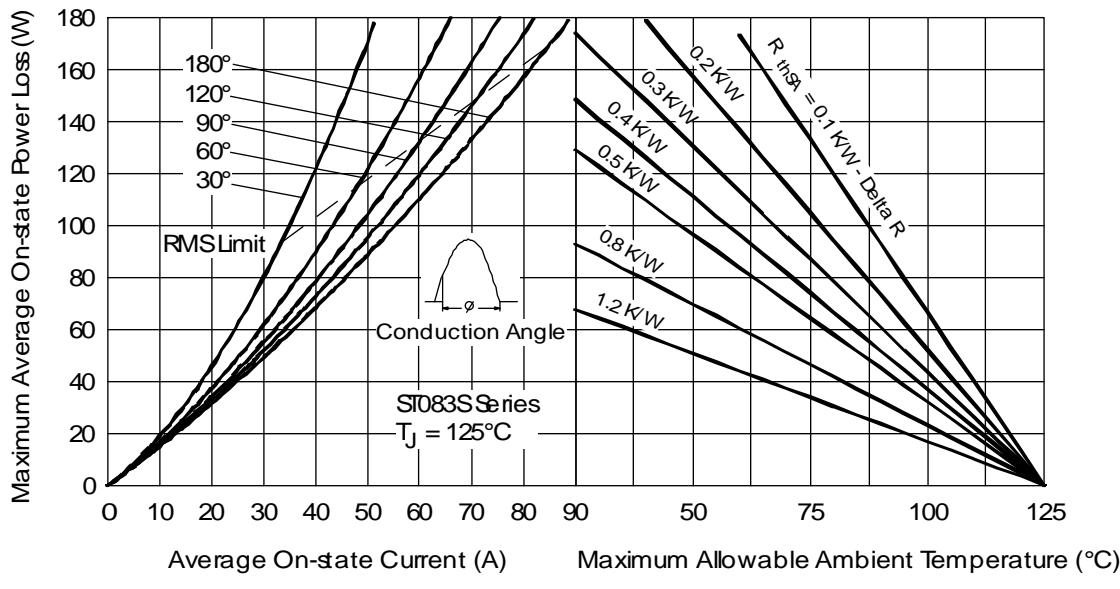
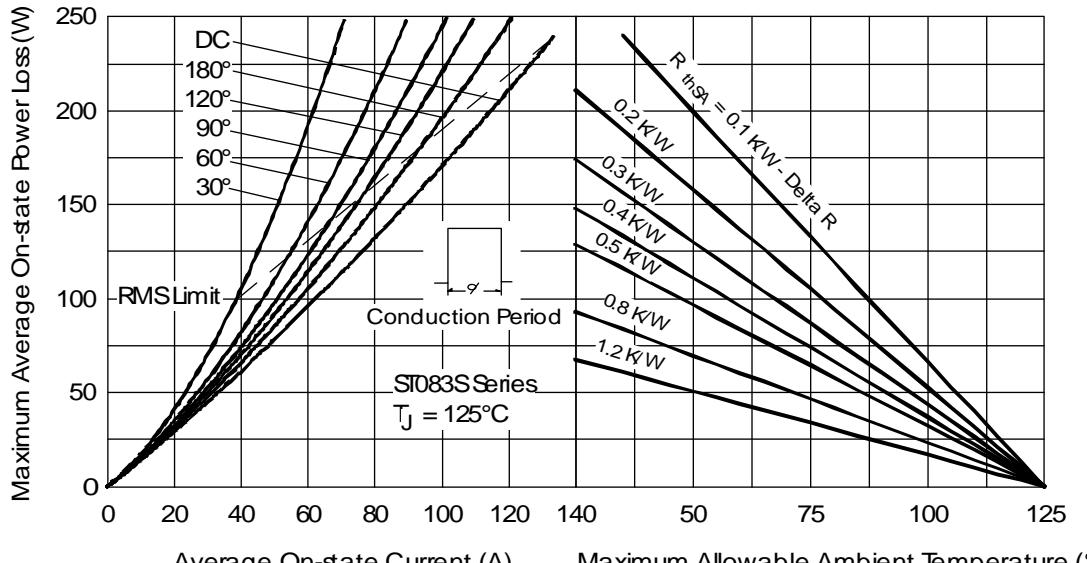


Fig. 3 - On-state Power Loss Characteristics



## ST083S Series

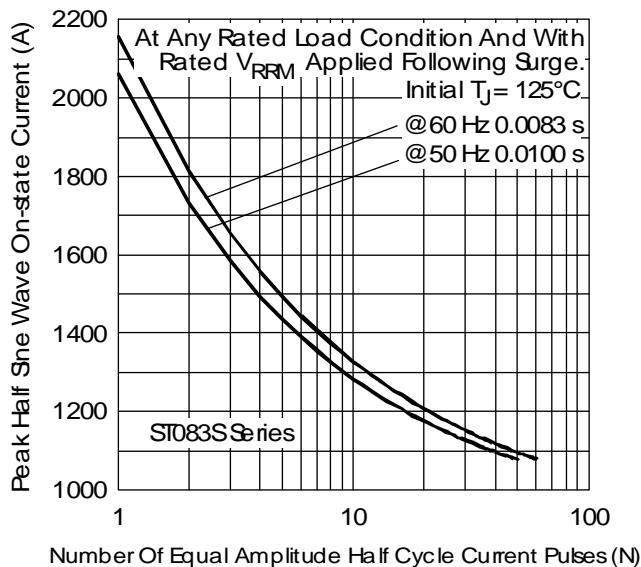


Fig. 5 - Maximum Non-repetitive Surge Current

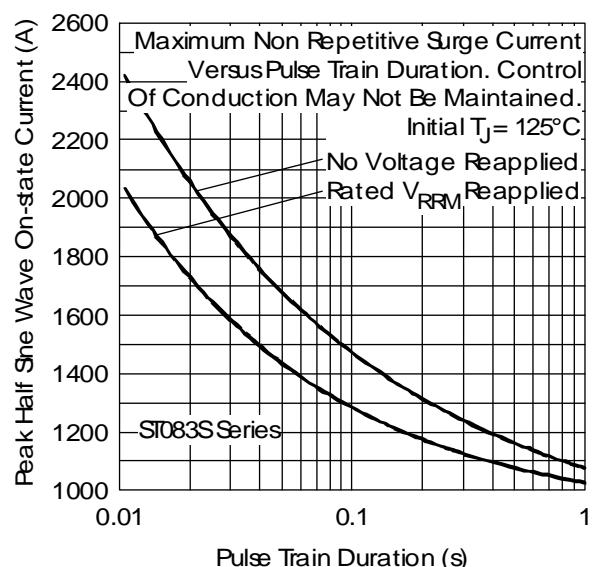


Fig. 6 - Maximum Non-repetitive Surge Current

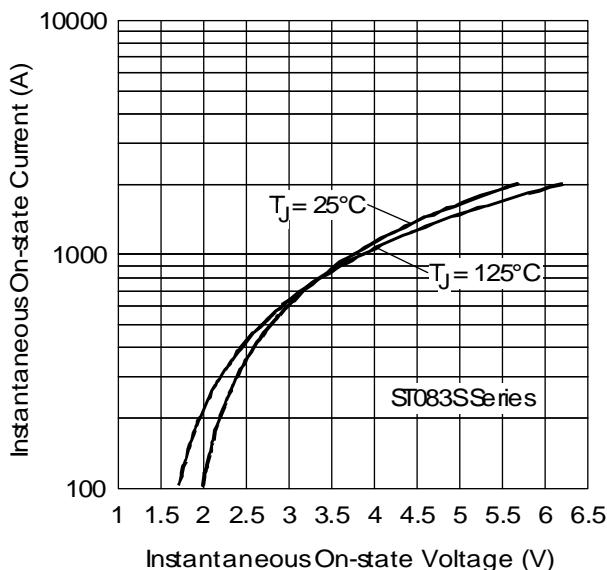


Fig. 7 - On-state Voltage Drop Characteristics

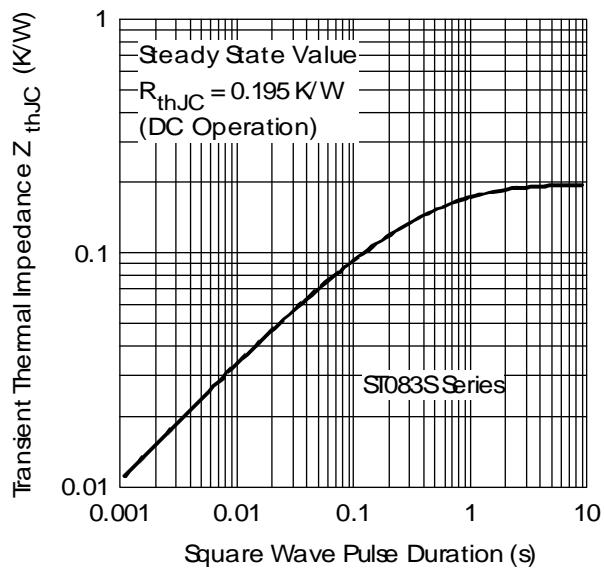
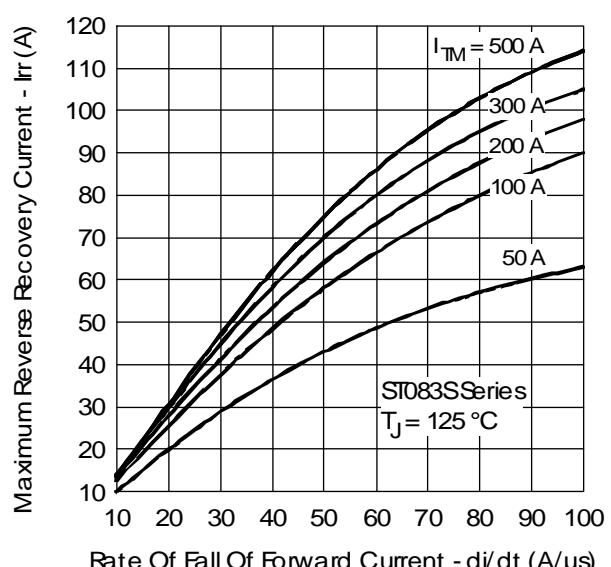
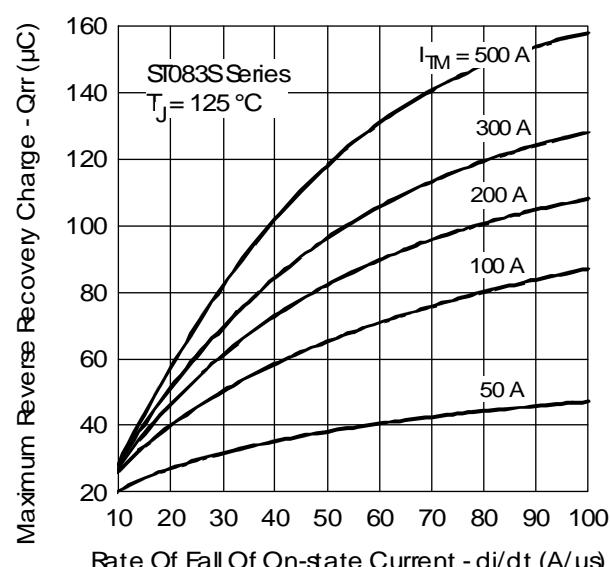


Fig. 8 - Thermal Impedance Z<sub>thJC</sub> Characteristic



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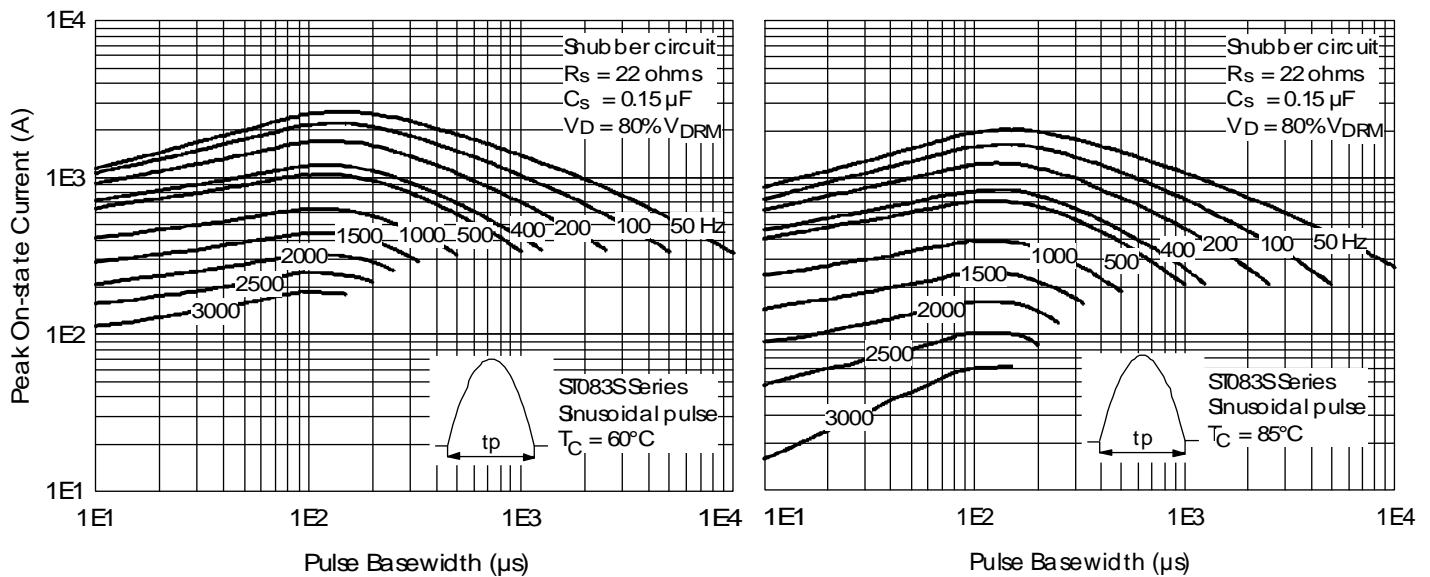


Fig. 11 - Frequency Characteristics

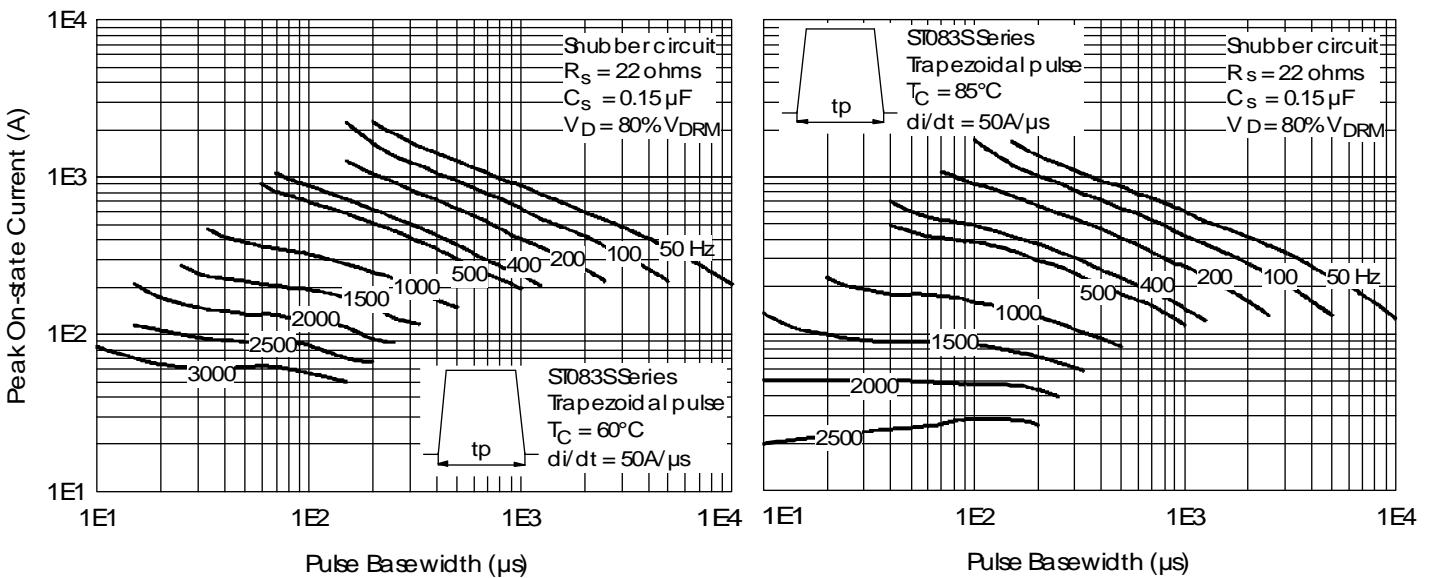
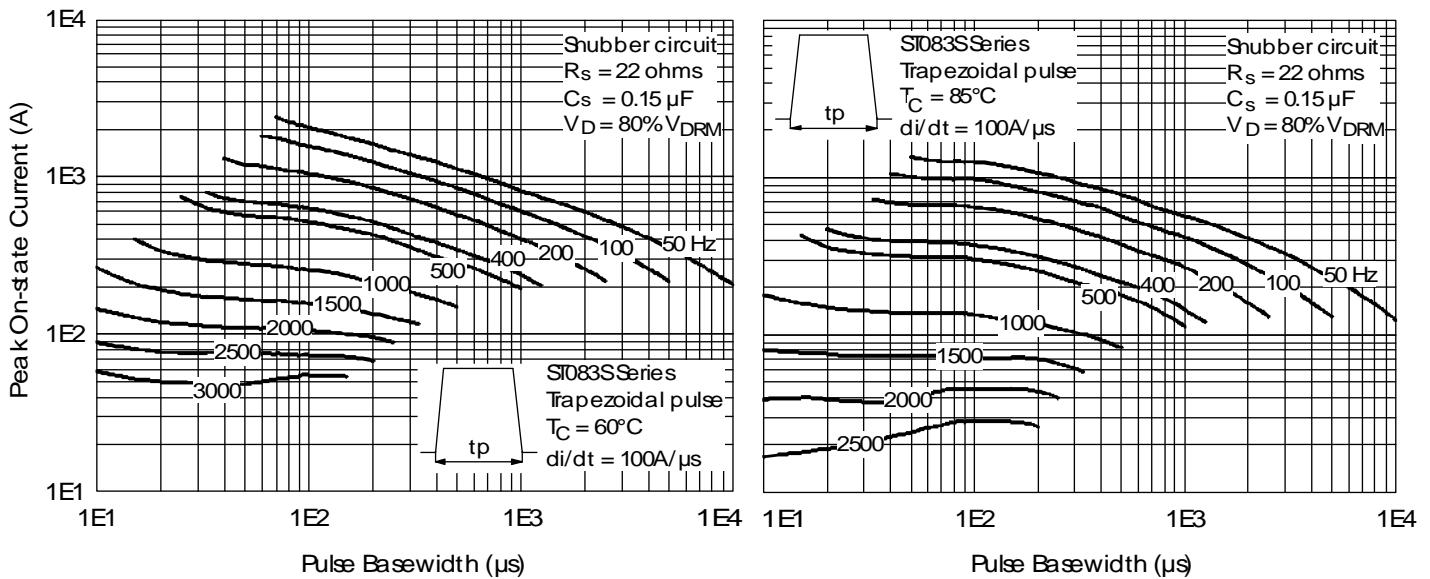


Fig. 12 - Frequency Characteristics



## ST083S Series

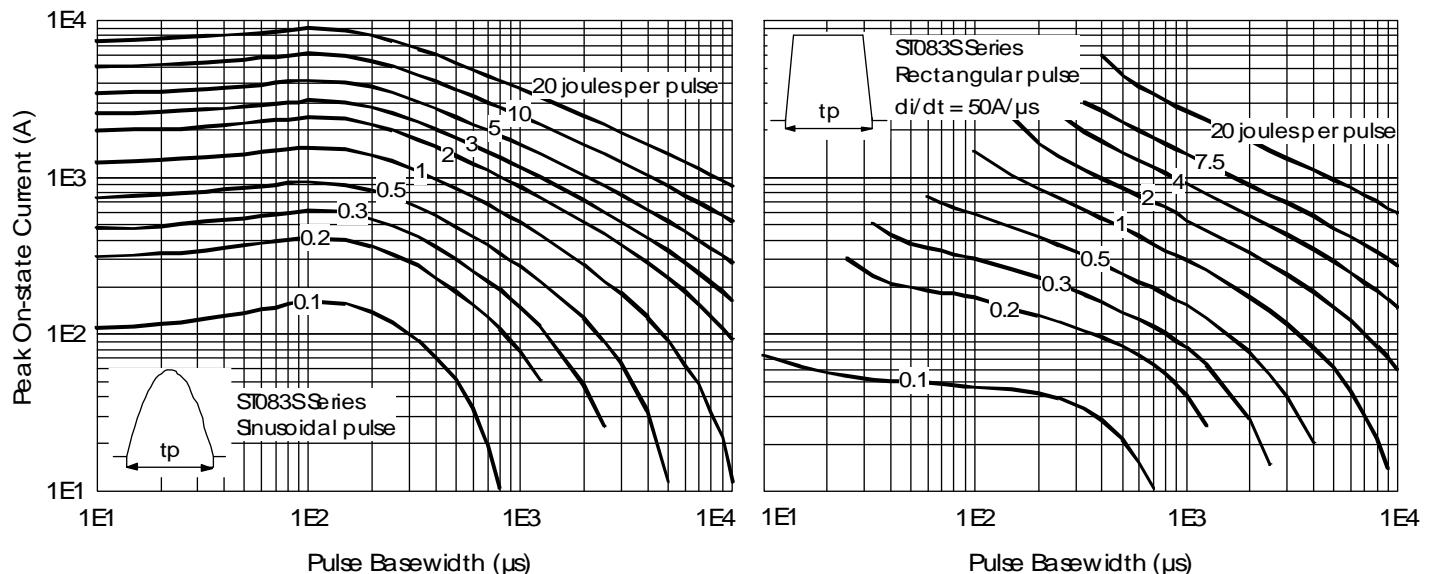


Fig. 14 - Maximum On-state Energy Power Loss Characteristics

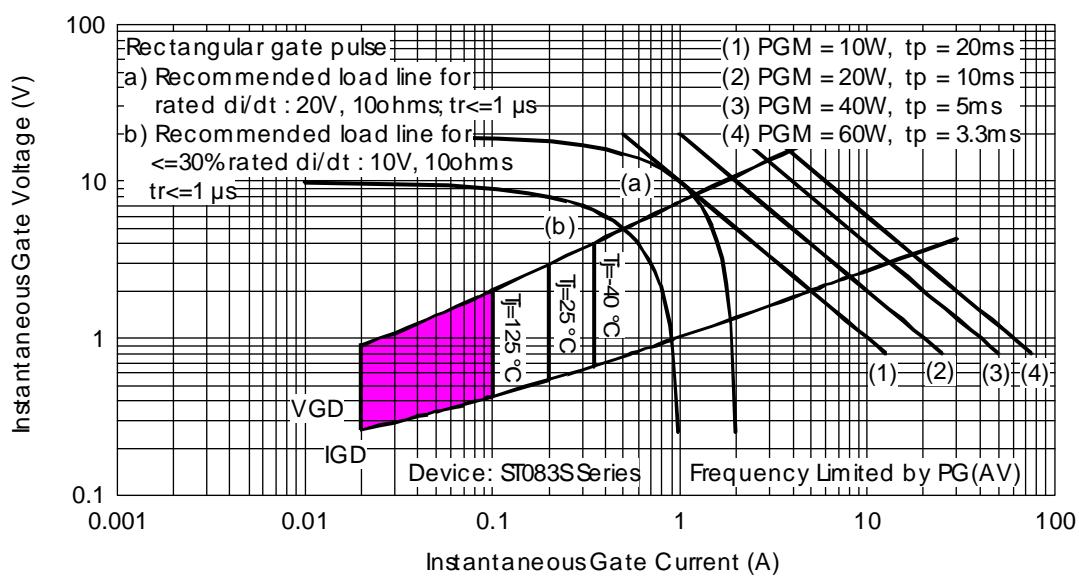


Fig. 15 - Gate Characteristics